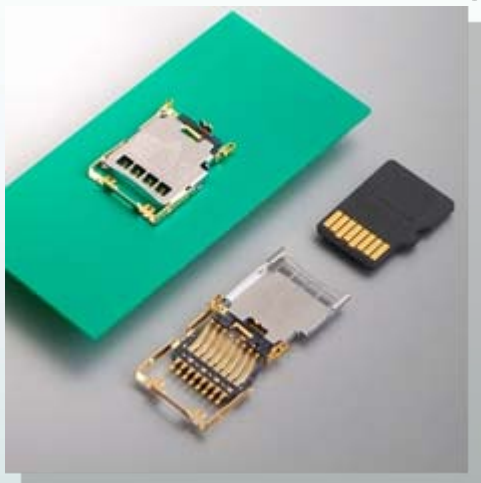


ST1W008S4G & ST1W008S4K

Super low profile (H=1.4mm) MicroSD hinge connector

Product Release



FEATURES

The ST1 Shrink Type has now been developed. This hinge-type connector maintains high mechanical and electrical performance but with a 40% reduction in volume and a 20% reduction in mounting area from the previous product, and an overall smallest-in-class size in the industry.

GENERAL SPECIFICATIONS

- ❑ No. of Contacts: 8pos. + 2 pos. (only for D-SW type)
- ❑ Rated Current: 0.5 A
- ❑ Insulation Resistance: 1,000 M ohm min.
- ❑ Contact Resistance: 100 m ohm max.
- ❑ Dielectric Withstanding Voltage: AC500 Vr.m.s. per minute
- ❑ Operating Temperature: -25 Deg. C to +85 Deg. C
- ❑ Durability: 10,000 times
- ❑ Storage Temperature: -10 Deg. C to +60 Deg. C
- ❑ Temperature Rise: 30 Deg. C rise max.

TARGET APPLICATIONS

- ❑ General small devices
 - Smartphone & Cell Phone
 - e-book
 - Handheld devices
- etc.

- ❑ Push-slide structure connector
- ❑ Balanced EMI control through 4 hold-down grounding points.
- ❑ Slim design with 1.4mm height, 15.5mm depth, 11.9mm width.
- ❑ Compatible with second reflow due to reduced weight.
- ❑ Available with and without card insertion detection structure (D-SW), normally open. Part number:
 - ❑ P/N:ST1W008S4GR2000 (without insertion detection structure)
 - ❑ P/N:ST1W008S4KR2000 (with insertion detection structure).
- ❑ Locking structure prevents falling off of cover when dropped.

Enclosed you will find a Component Product Information guide and JACS for the series.

For further details and promotional samples, please contact Marketing Resources



Technology to Inspire Innovation

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